

DOSEMI

IGBT

DG120X07T2

650V/120A IGBT with Diode

General Description

DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as general inverters and UPS.

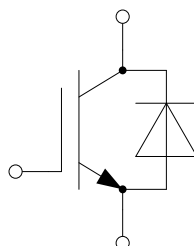
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- Maximum junction temperature 175°C
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Equivalent Circuit Schematic



Type	Package	Marking	Shipping
DG120X07T2	TO-247PLUS-3L	DG120X07T2	30Units/Tube

Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage Transient Gate-Emitter Voltage	± 20 -25/+30	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	200 ⁽¹⁾ 120	A
I_{CM}	Pulsed Collector Current t_p limited by T_{vjmax}	360	A
P_D	Maximum Power Dissipation @ $T_{vj}=175^{\circ}\text{C}$	893	W

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_F	Diode Continuous Forward Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	177 120	A
I_{FM}	Diode Pulsed Current t_p limited by T_{vjmax}	360	A

Discrete

Symbol	Description	Values	Unit
T_{vjop}	Operating Junction Temperature	-40 to +175	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
T_S	Soldering Temperature, 1.6mm from case for 10s	260	$^{\circ}\text{C}$

(1) limited by bondwire

IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=120\text{A}, V_{GE}=15\text{V}, T_{vj}=25^{\circ}\text{C}$		1.40	1.85	V
		$I_C=120\text{A}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}$		1.70		
		$I_C=120\text{A}, V_{GE}=15\text{V}, T_{vj}=175^{\circ}\text{C}$		1.75		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1.92\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$	5.0	5.8	6.5	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			250	μA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			200	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		14.1		nF
C_{oes}	Output Capacitance			0.61		nF
C_{res}	Reverse Transfer Capacitance			0.42		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		0.86		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=120\text{A}, R_G=7.5\Omega, L_S=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=25^{\circ}\text{C}$		72		ns
t_r	Rise Time			143		ns
$t_{d(off)}$	Turn-Off Delay Time			187		ns
t_f	Fall Time			94		ns
E_{on}	Turn-On Switching Loss			5.28		mJ
E_{off}	Turn-Off Switching Loss			2.30		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=120\text{A}, R_G=7.5\Omega, L_S=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=150^{\circ}\text{C}$		78		ns
t_r	Rise Time			143		ns
$t_{d(off)}$	Turn-Off Delay Time			203		ns
t_f	Fall Time			131		ns
E_{on}	Turn-On Switching Loss			6.40		mJ
E_{off}	Turn-Off Switching Loss			3.08		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=120\text{A}, R_G=7.5\Omega, L_S=40\text{nH}, V_{GE}=\pm 15\text{V}, T_{vj}=175^{\circ}\text{C}$		80		ns
t_r	Rise Time			143		ns
$t_{d(off)}$	Turn-Off Delay Time			206		ns
t_f	Fall Time			141		ns
E_{on}	Turn-On Switching Loss			6.61		mJ
E_{off}	Turn-Off Switching Loss			3.23		mJ
I_{SC}	SC Data	$t_p \leq 6\mu\text{s}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}, V_{CC}=300\text{V}, V_{CEM} \leq 650\text{V}$		600		A

Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=120\text{A}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$		1.65	2.10	V
		$I_F=120\text{A}, V_{GE}=0\text{V}, T_{vj}=150^{\circ}\text{C}$		1.60		
		$I_F=120\text{A}, V_{GE}=0\text{V}, T_{vj}=175^{\circ}\text{C}$		1.60		
t_{rr}	Diode Reverse Recovery Time	$V_R=300\text{V}, I_F=120\text{A},$ $-di/dt=640\text{A}/\mu\text{s}, L_S=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=25^{\circ}\text{C}$		114		ns
Q_r	Recovered Charge			1.65		μC
I_{RM}	Peak Reverse Recovery Current			24		A
E_{rec}	Reverse Recovery Energy			0.25		mJ
t_{rr}	Diode Reverse Recovery Time	$V_R=300\text{V}, I_F=120\text{A},$ $-di/dt=630\text{A}/\mu\text{s}, L_S=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=150^{\circ}\text{C}$		202		ns
Q_r	Recovered Charge			4.08		μC
I_{RM}	Peak Reverse Recovery Current			32		A
E_{rec}	Reverse Recovery Energy			0.70		mJ
t_{rr}	Diode Reverse Recovery Time	$V_R=300\text{V}, I_F=120\text{A},$ $-di/dt=633\text{A}/\mu\text{s}, L_S=40\text{nH},$ $V_{GE}=-15\text{V}, T_{vj}=175^{\circ}\text{C}$		214		ns
Q_r	Recovered Charge			4.62		μC
I_{RM}	Peak Reverse Recovery Current			34		A
E_{rec}	Reverse Recovery Energy			0.79		mJ

Discrete Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT)			0.168	K/W
	Junction-to-Case (per Diode)			0.369	
R_{thJA}	Junction-to-Ambient		40		K/W

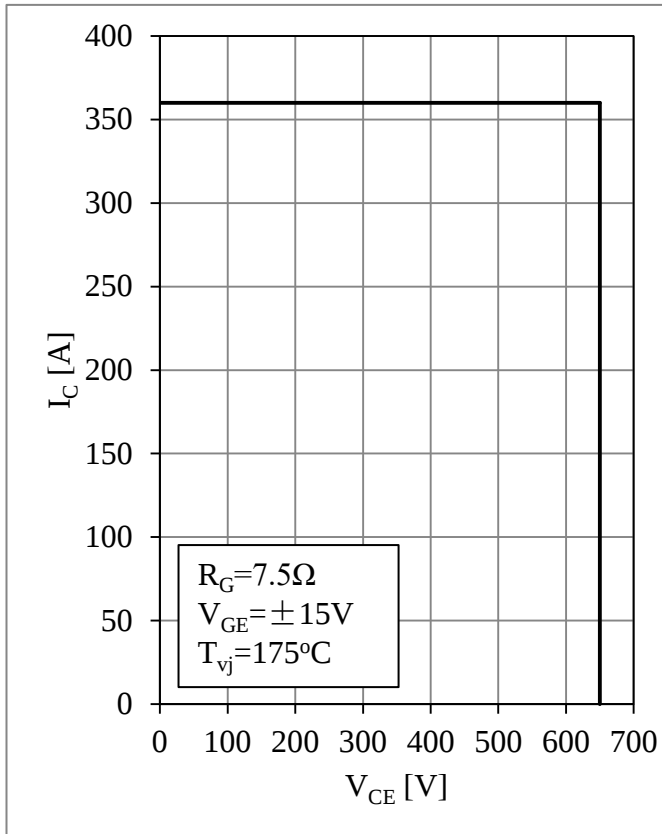


Fig 1. RBSOA

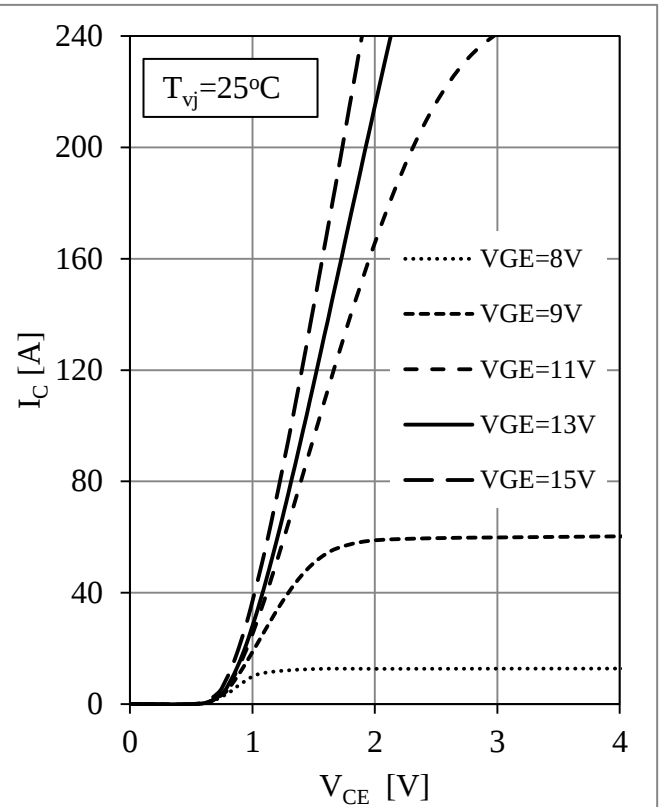


Fig 2. IGBT Output Characteristics

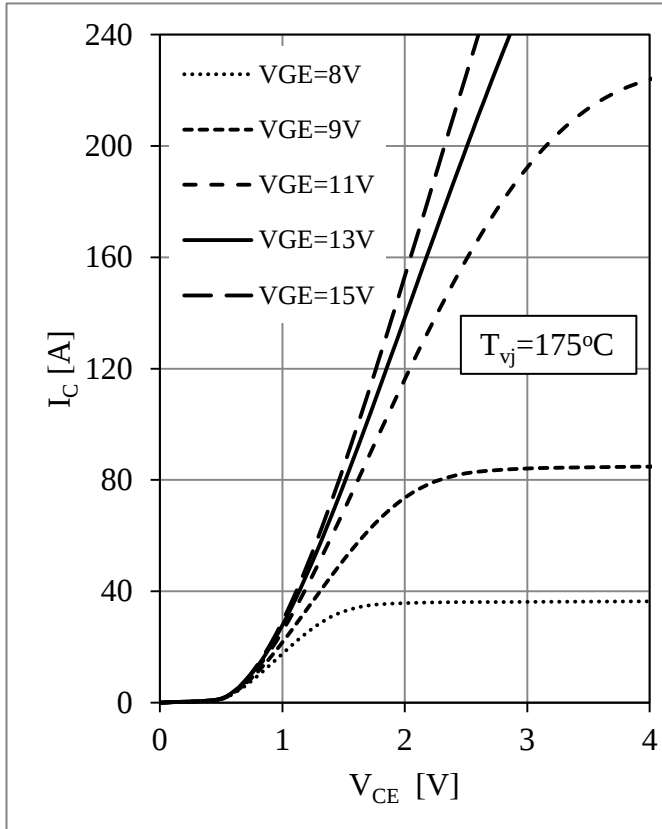


Fig 3. IGBT Output Characteristics

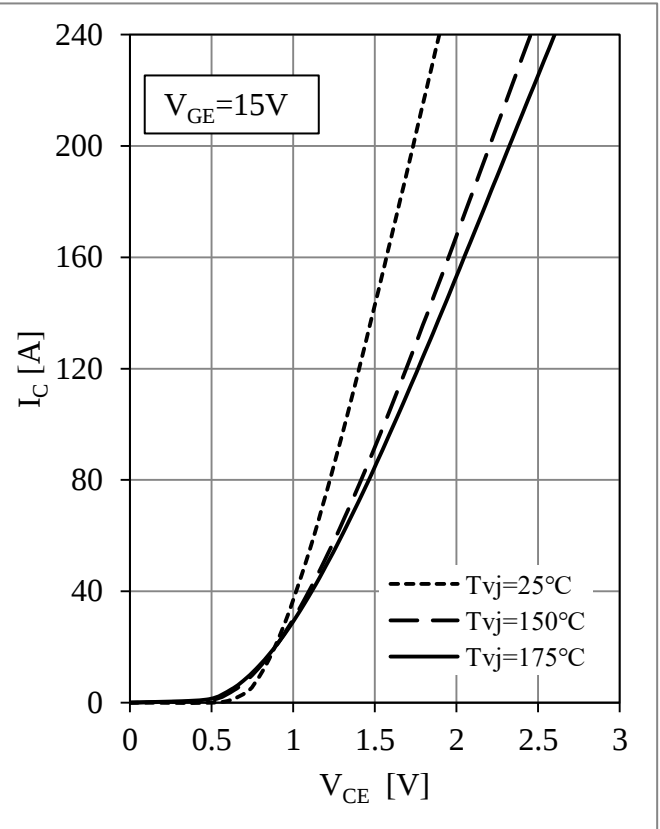


Fig 4. IGBT Output Characteristics

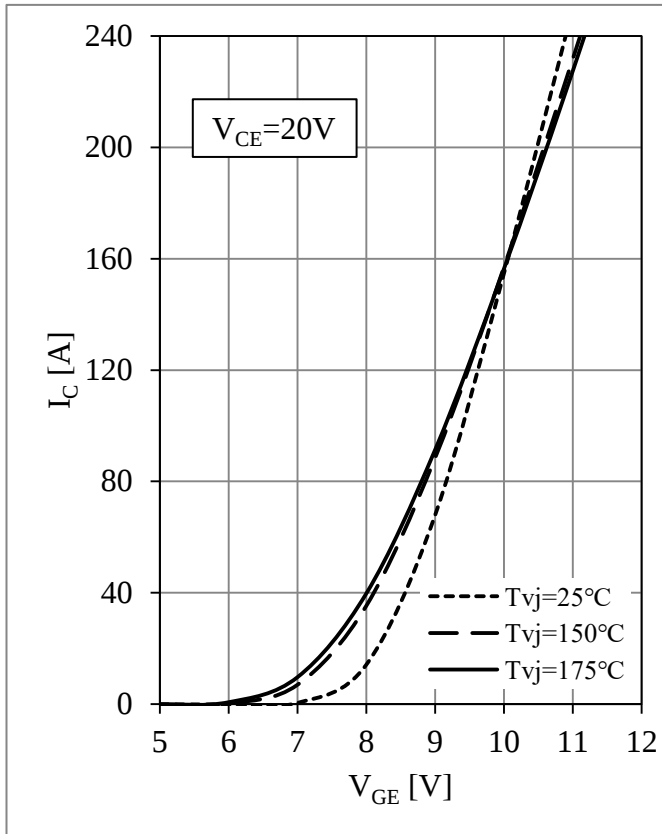
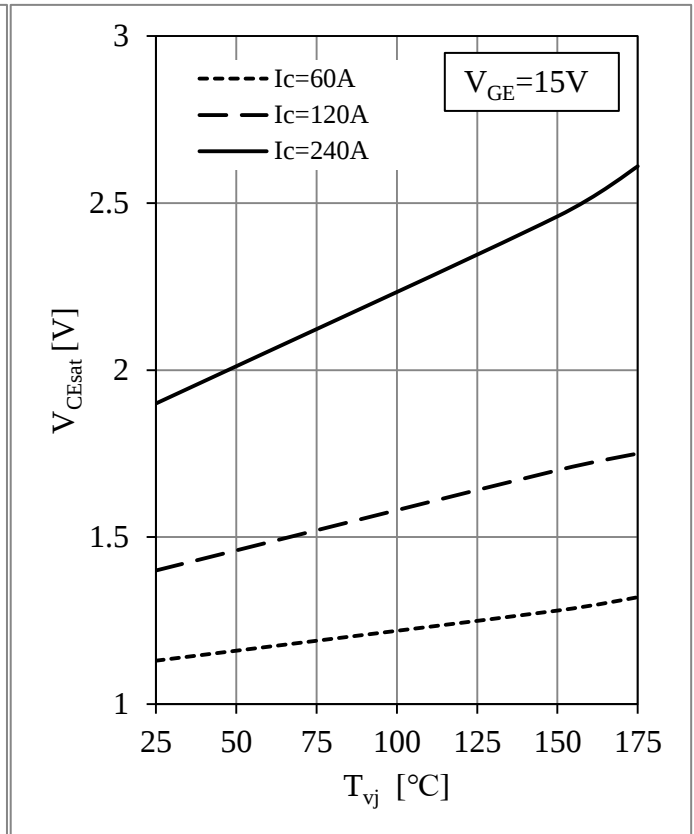
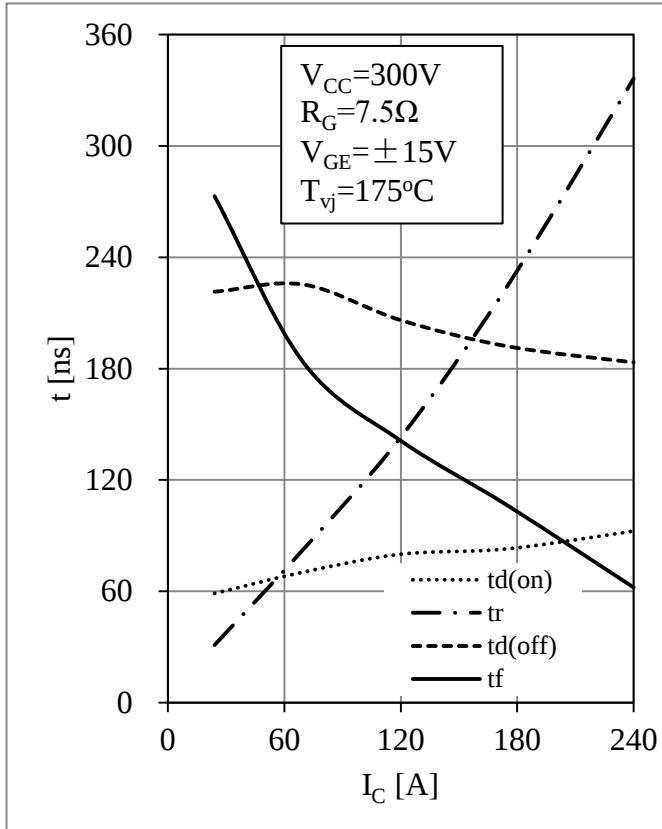
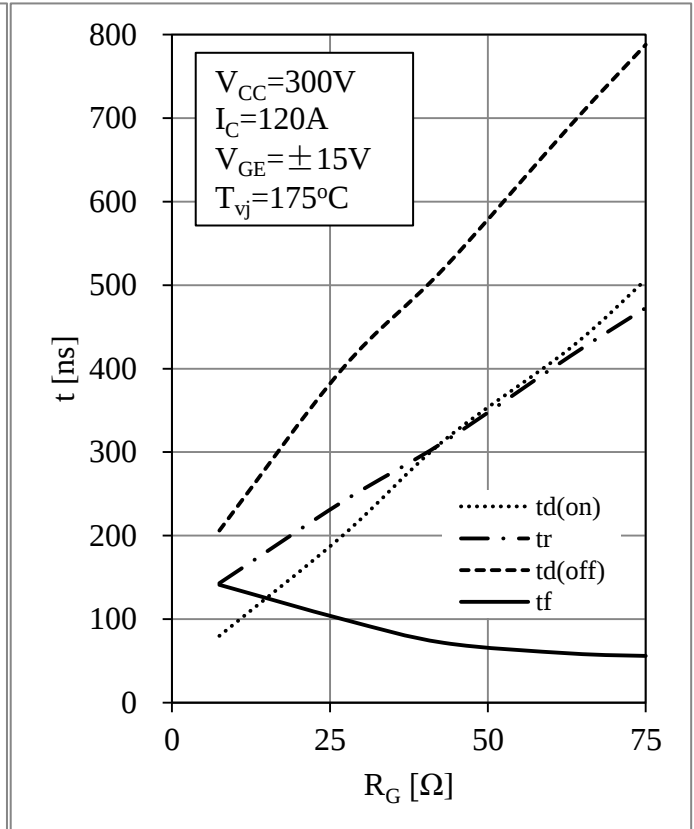
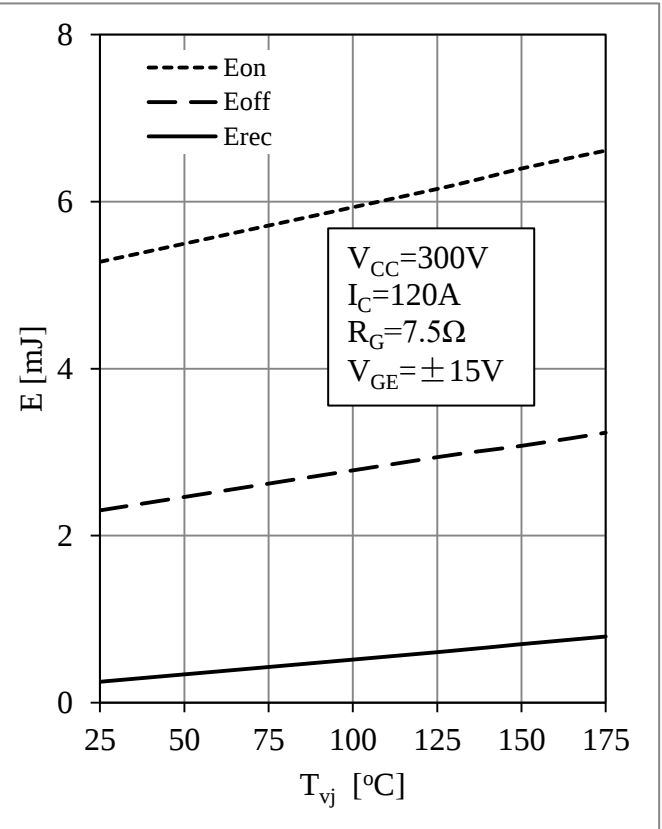
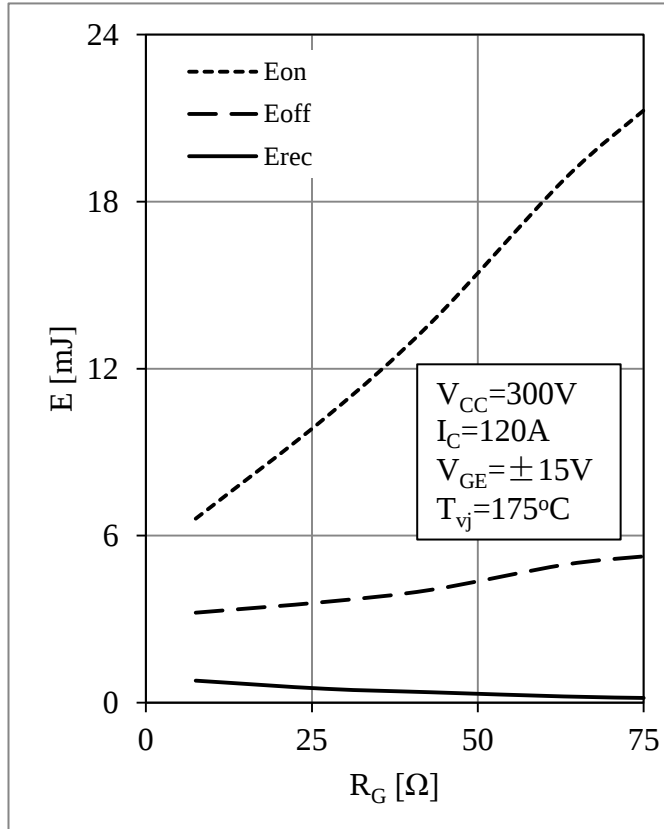
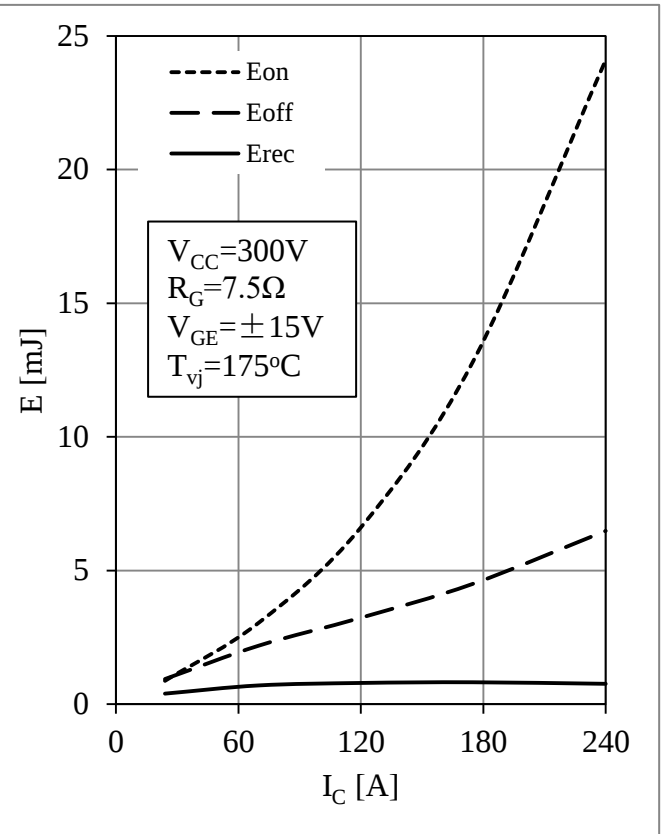
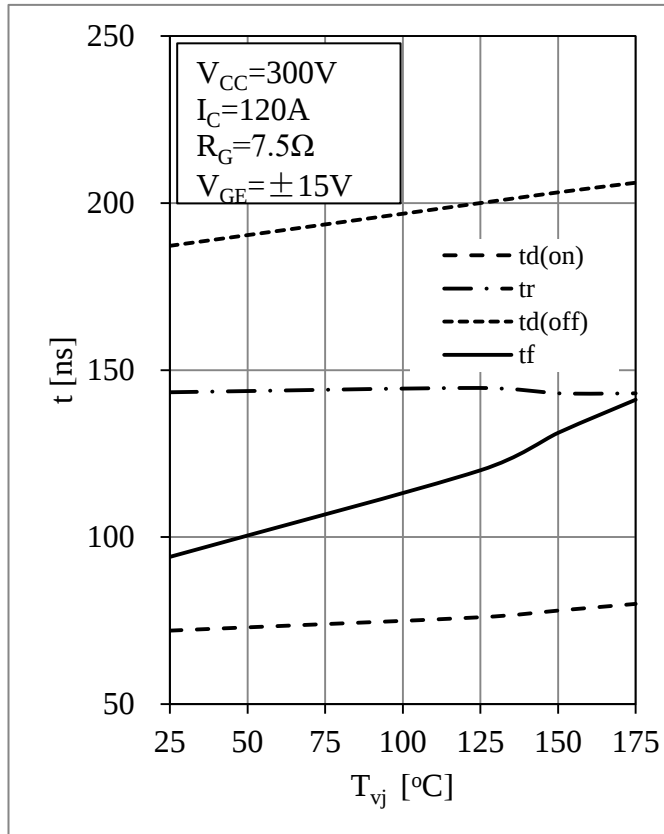


Fig 5. IGBT Transfer Characteristics

Fig 6. Collector-emitter saturation voltage vs T_{vj} Fig 7. IGBT Switching Times vs. I_C Fig 8. IGBT Switching Times vs. R_G

Fig 11. Switching Energy Loss vs. R_G Fig 12. Switching Energy Loss vs. T_{vj}

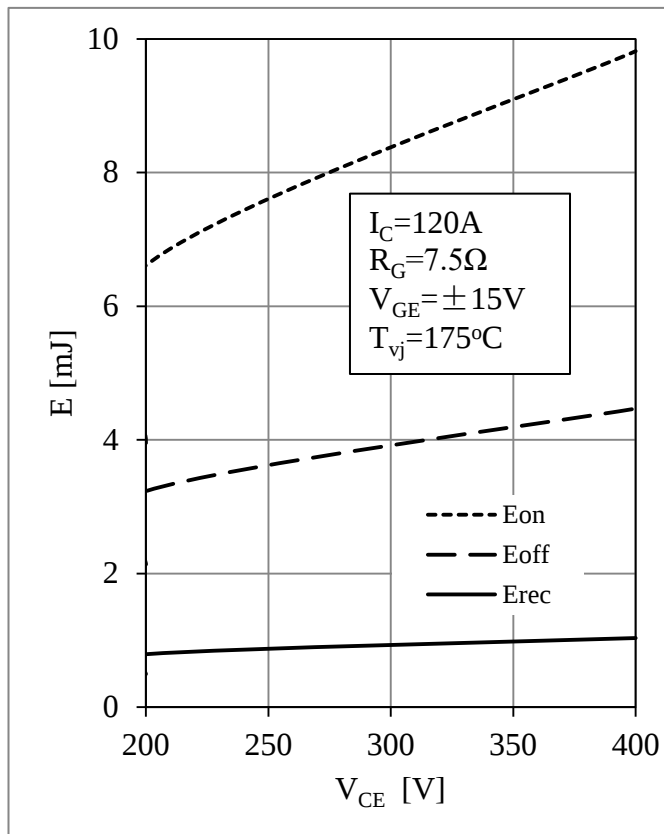
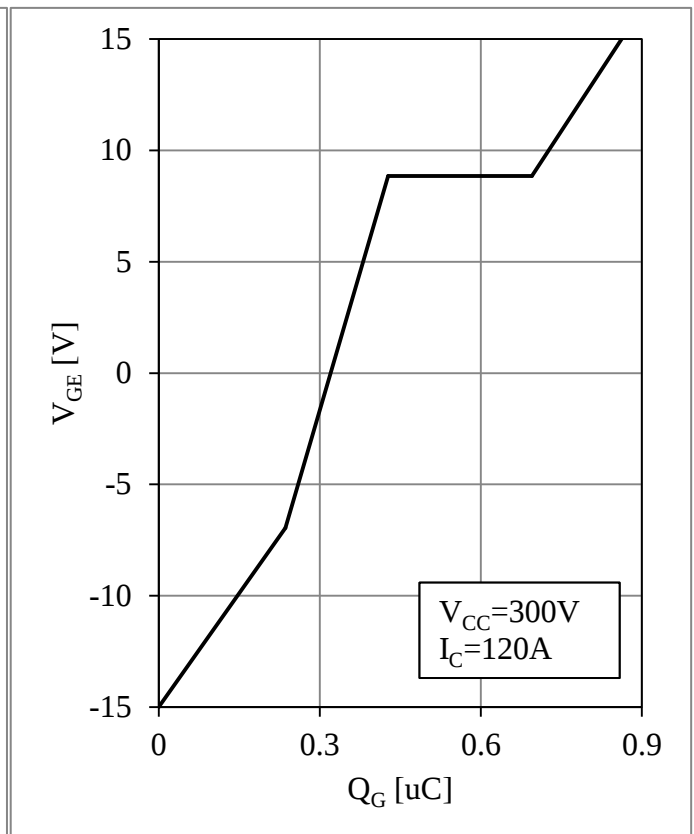
Fig 13. Switching Energy Loss vs. V_{CE} 

Fig 14. IGBT Gate Charge Characteristic

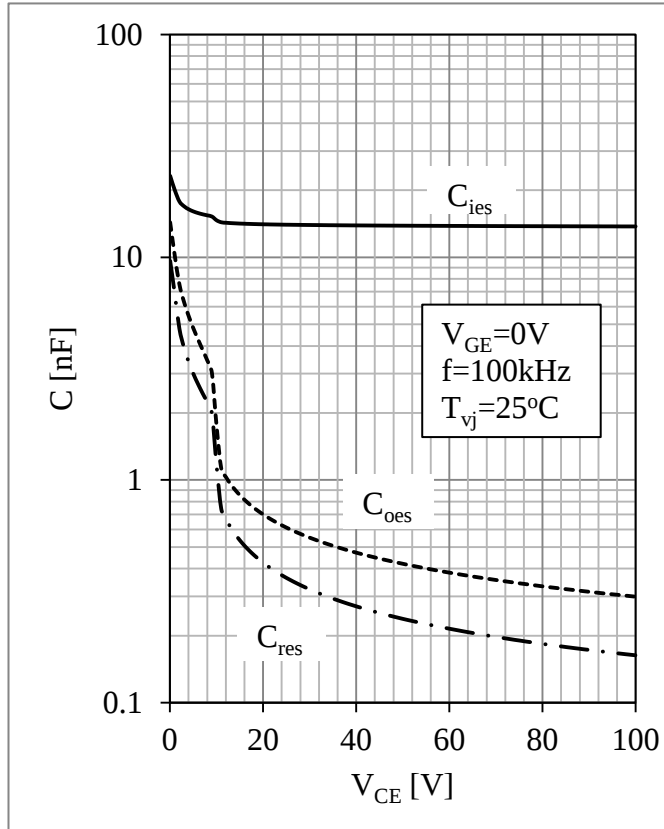


Fig 15. IGBT Capacity Characteristic

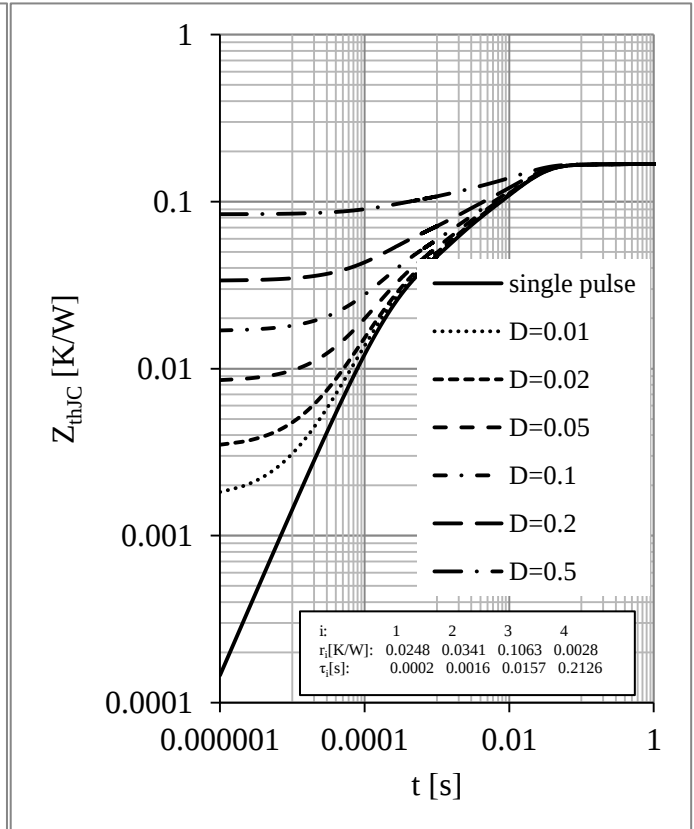


Fig 16. IGBT Transient Thermal Impedance

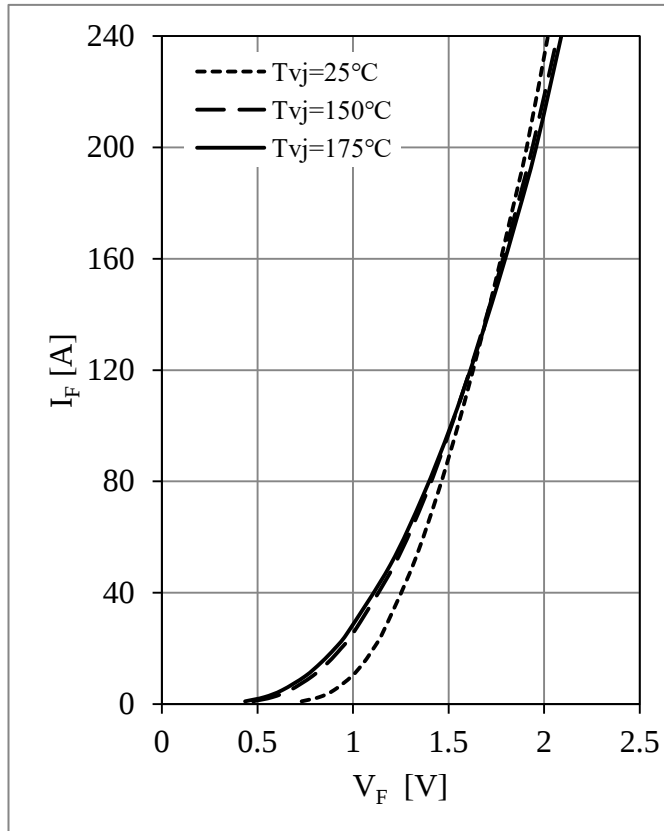
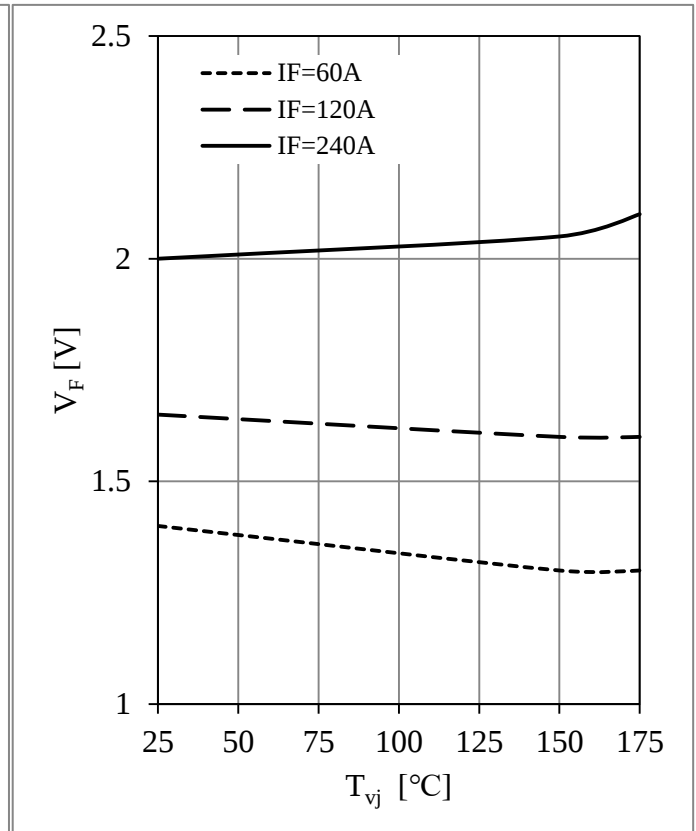
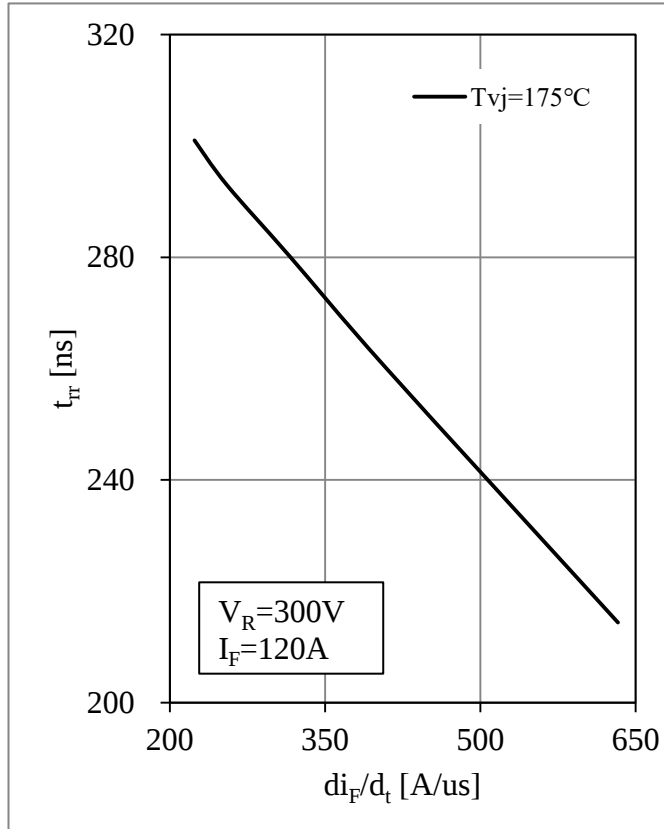
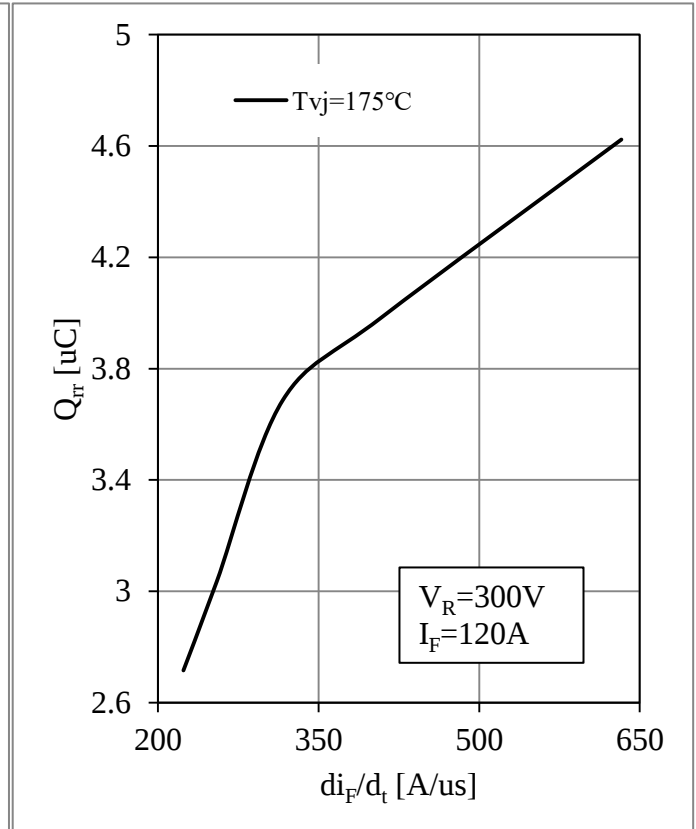


Fig 17. Diode Forward Characteristics

Fig 18. Diode Forward Voltage $V_s T_{vj}$ Fig 19. Reverse Recovery Time vs. di_F/dt Fig 20. Reverse Recovery Charge vs. di_F/dt

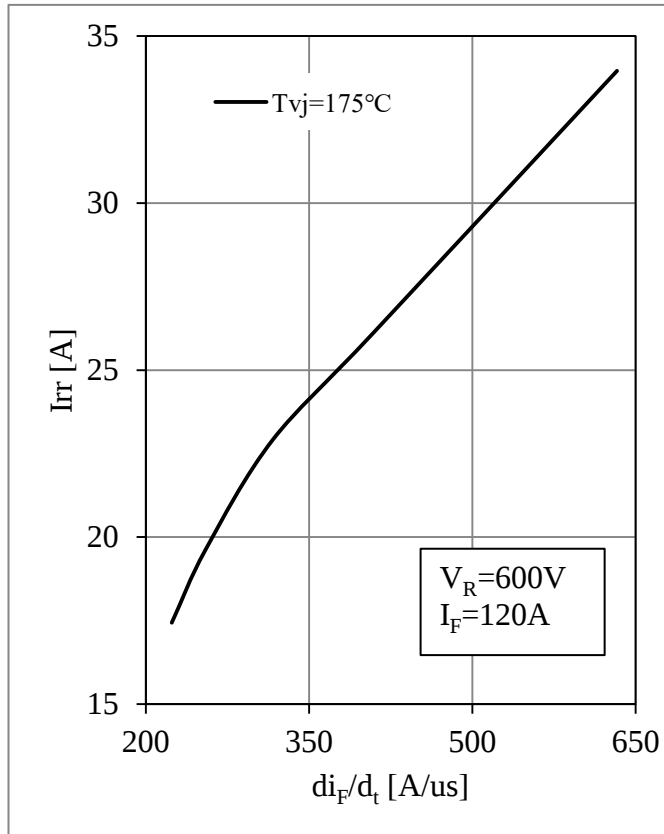
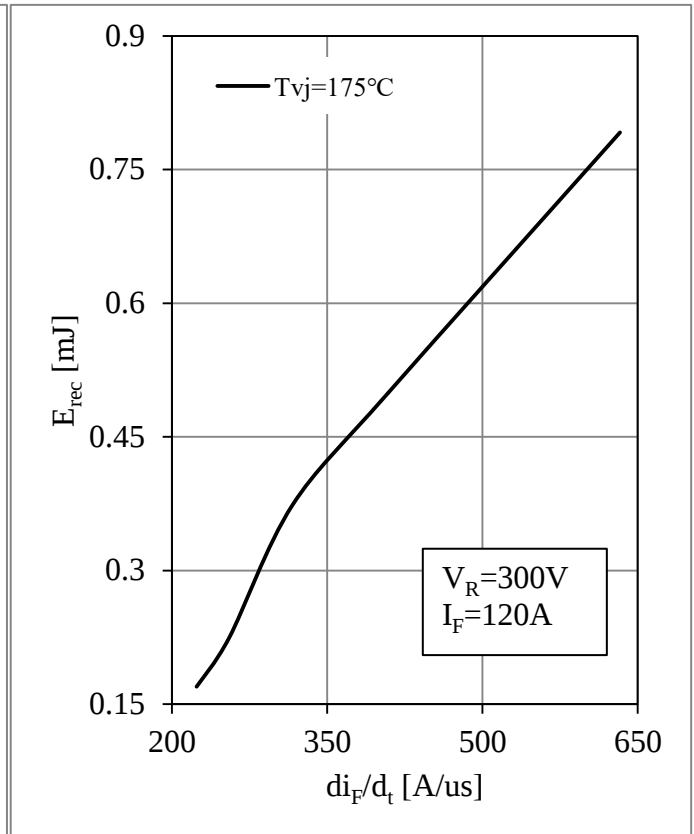
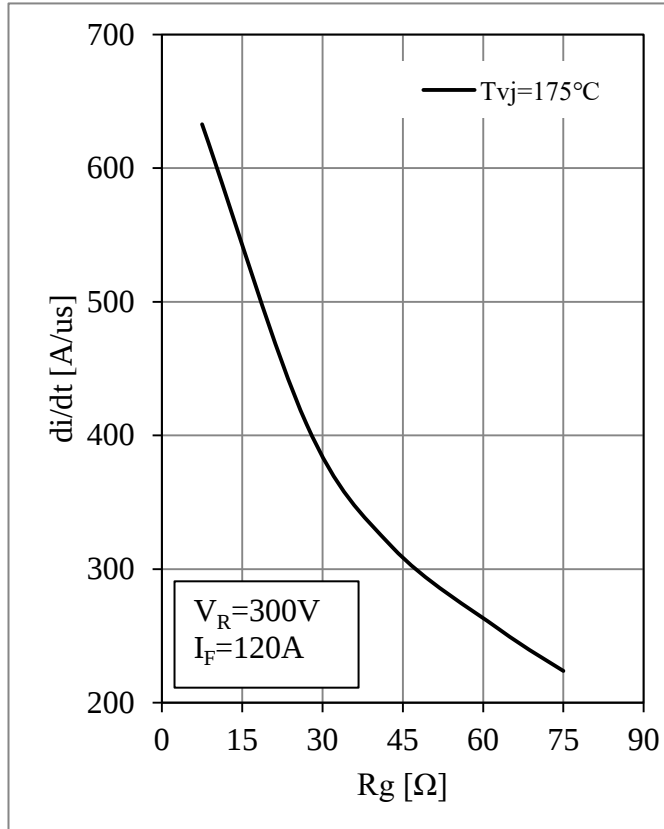
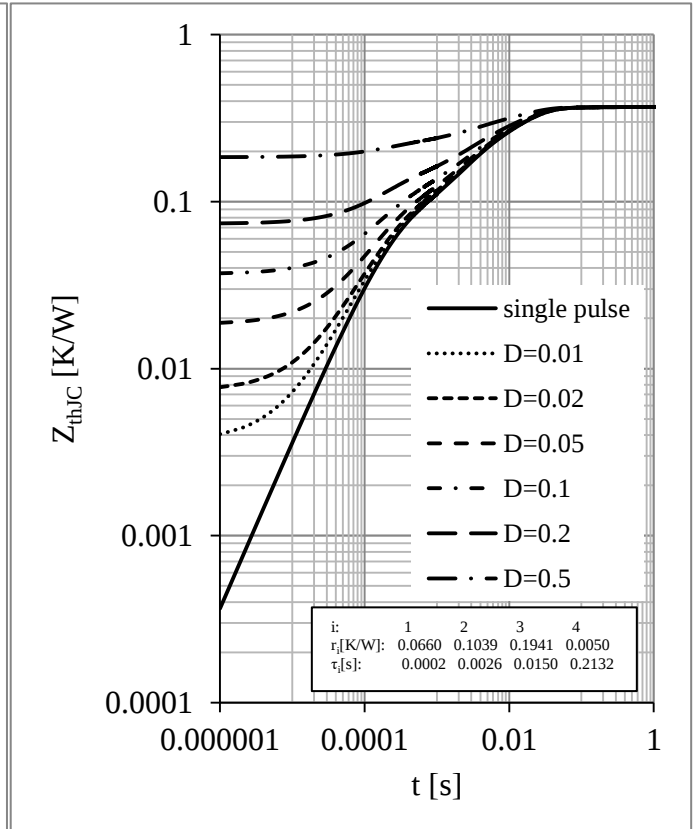
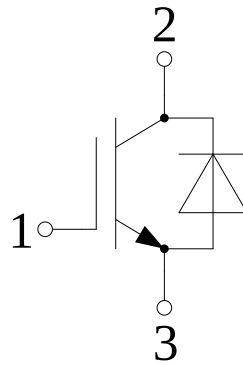
Fig 21. Reverse Recovery Current vs. di_F/dt Fig 22. Reverse Energy Losses vs. di_F/dt Fig 23. di_F/dt vs R_g 

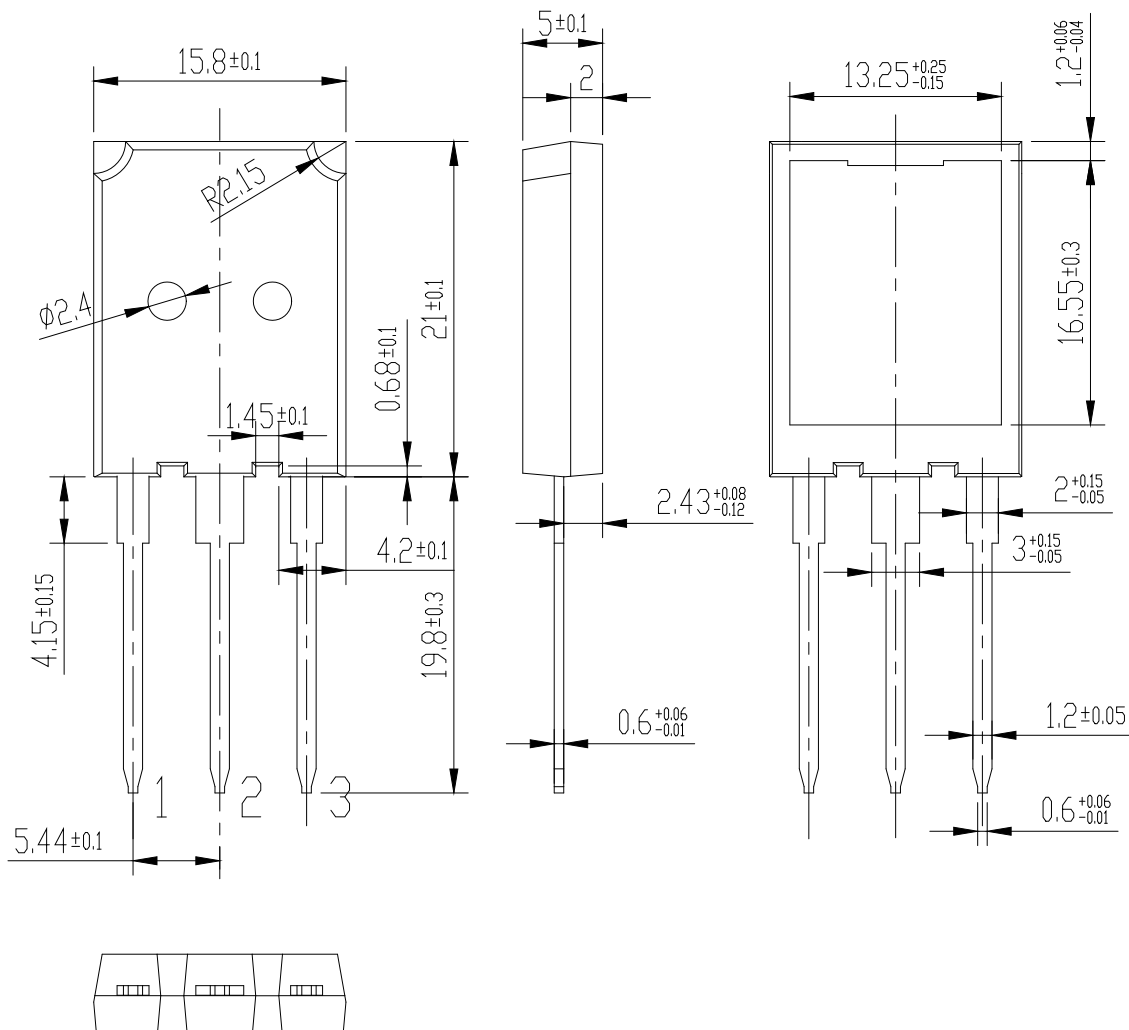
Fig 24. Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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